IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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Thank you for your cooperation and understanding,

WeEn Semiconductors

founded by NXP

BUJD105AD

NPN power transistor with integrated diode

11 October 2016 **Product data sheet**

1. General description

High voltage, high speed, planar passivated NPN power switching transistor with integrated anti-parallel E-C diode in a SOT428 (DPAK) surface mountable plastic package.

2. Features and benefits

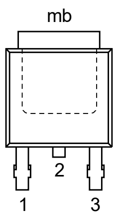
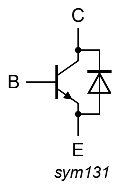
- Fast switching
- High voltage capability
- Integrated anti-parallel E-C diode
- Surface mountable plastic package
- Very low switching and conduction losses

3. Applications

- DC-to-DC converters
- Electronic lighting ballasts
- Inverters
- Motor control systems

4. Pinning information

Table 1. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 DPAK (SOT428)	
2	C	collector[1]		
3	E	emitter		

[1] It is not possible to make a connection to pin 2 of the SOT428 (DPAK) package.

5. Ordering information

Table 2. Ordering information

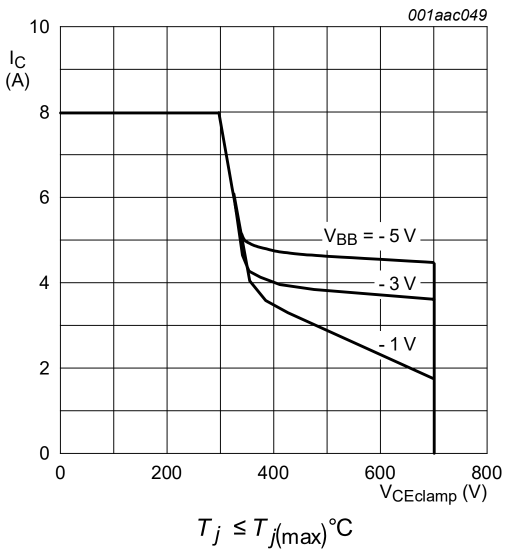
Type number	Package		
	Name	Description	Version
BUJD105AD	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

6. Limiting values

Table 3. Limiting values

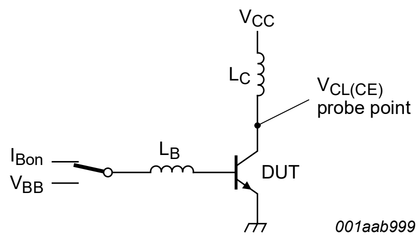
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CESM}	collector-emitter peak voltage	V_{BE} = 0 V		-	700	V
V_{CBO}	collector-base voltage	I_E = 0 A		-	700	V
V_{CEO}	collector-emitter voltage	I_B = 0 A		-	400	V
I_C	collector current	DC; Fig. 1; Fig. 2		-	8	A
I_{CM}	peak collector current	Fig. 1; Fig. 2		-	16	A
I_B	base current	DC		-	4	A
I_{BM}	peak base current			-	8	A
P_{tot}	total power dissipation	T_{mb} ≤ 25 °C; Fig. 3		-	80	W
T_{stg}	storage temperature			-65	150	°C
T_j	junction temperature			-	150	°C



$T_j \leq T_{j(max)}$°C

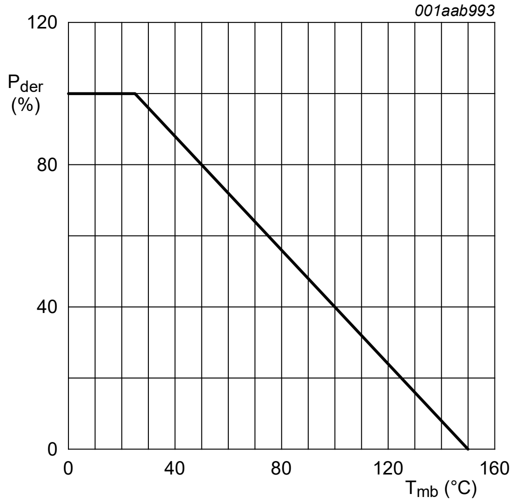
Fig. 1. Reverse bias safe operating area



$V_{CL(CE)} \leq 1000\ V; V_{CC} = 150\ V; V_{BB} = -5\ V;$

$L_B = 1\ \mu H; L_C = 200\ \mu H$

Fig. 2. Test circuit for reverse bias safe operating area



$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\,\%$$

Fig. 3. Normalized total power dissipation as a function of mounting base temperature

7. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4		-	-	1.56	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	printed circuit board (FR4) mounted; minimum footprint; Fig. 5		-	75	-	K/W

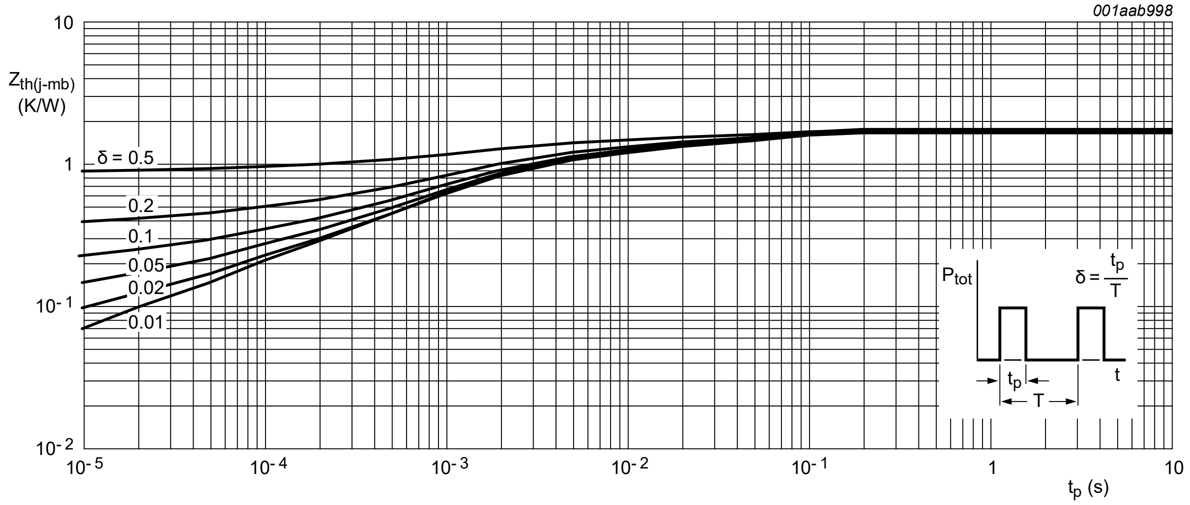


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse width

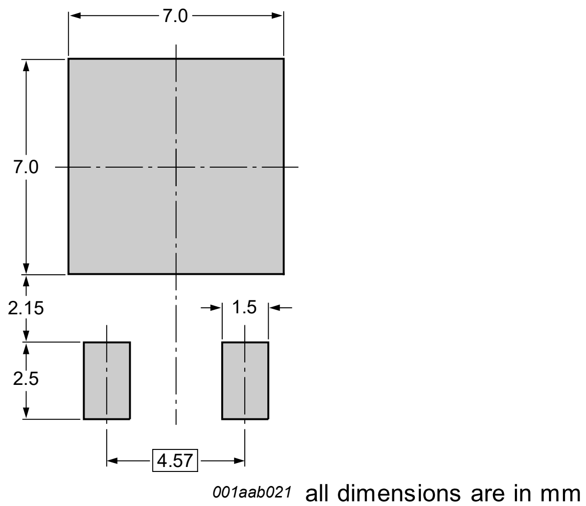


Fig. 5. Minimum footprint SOT428

8. Characteristics

Table 5. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{CES}	collector-emitter cut-off current (base shorted)	V_{BE} = 0 V; V_{CE} = 700 V; T_j = 25 °C	[1]	-	-	0.2	mA
		V_{BE} = 0 V; V_{CE} = 700 V; T_j = 125 °C	[1]	-	-	0.5	mA
I_{CBO}	collector-base cut-off current (emitter open)	V_{CB} = 700 V; I_E = 0 A	[1]	-	-	0.2	mA
I_{CEO}	collector-emitter cut-off current (base open)	V_{CE} = 400 V; I_B = 0 A	[1]	-	-	0.1	mA
I_{EBO}	emitter-base cut-off current (collector open)	V_{EB} = 9 V; I_C = 0 A		-	-	10	mA
V_{CEsat}	collector-emitter saturation voltage	I_C = 4 A; I_B = 0.8 A; Fig. 6; Fig. 7		-	0.35	1	V
V_{BEsat}	base-emitter saturation voltage	I_C = 4 A; I_B = 0.8 A; Fig. 8		-	1	1.5	V
V_F	forward voltage	I_F = 4 A; T_j = 25 °C		-	1.07	1.5	V
h_{FE}	DC current gain	I_C = 4 A; V_{CE} = 5 V; T_{mb} = 25 °C; Fig. 9; Fig. 10		8	12.5	-	
		I_C = 1 mA; V_{CE} = 5 V; T_{mb} = 25 °C		10	17	34	
		I_C = 500 mA; V_{CE} = 5 V; T_{mb} = 25 °C		13	22	36	
Dynamic characteristics							
t_{on}	turn-on time	I_C = 5 A; I_{Bon} = 1 A; I_{Boff} = -1 A; R_L = 75 Ω; T_j = 25 °C; resistive load; Fig. 11; Fig. 12		-	0.65	1	μs
t_s	storage time			-	1.8	2.5	μs
		I_C = 5 A; I_{Bon} = 1 A; V_{BB} = -5 V; L_B = 1 μH; T_j = 25 °C; inductive load; Fig. 13; Fig. 14		-	1.2	1.7	μs
		I_C = 5 A; I_{Bon} = 1 A; V_{BB} = -5 V; L_B = 1 μH; T_j = 100 °C; inductive load; Fig. 13; Fig. 14		-	1.4	1.9	μs
t_f	fall time	I_C = 5 A; I_{Bon} = 1 A; V_{BB} = -5 V; L_B = 1 μH; T_{mb} = 25 °C; inductive load; Fig. 13; Fig. 14		-	0.02	0.05	μs
		I_C = 5 A; I_{Bon} = 1 A; V_{BB} = -5 V; L_B = 1 μH; T_{mb} = 100 °C; inductive load; Fig. 13; Fig. 14		-	0.025	0.1	μs
		I_C = 5 A; I_{Bon} = 1 A; I_{Boff} = -1 A; R_L = 75 Ω; resistive load; Fig. 11; Fig. 12		-	0.3	0.5	μs

[1] Measured with half-sine wave voltage (curve tracer).

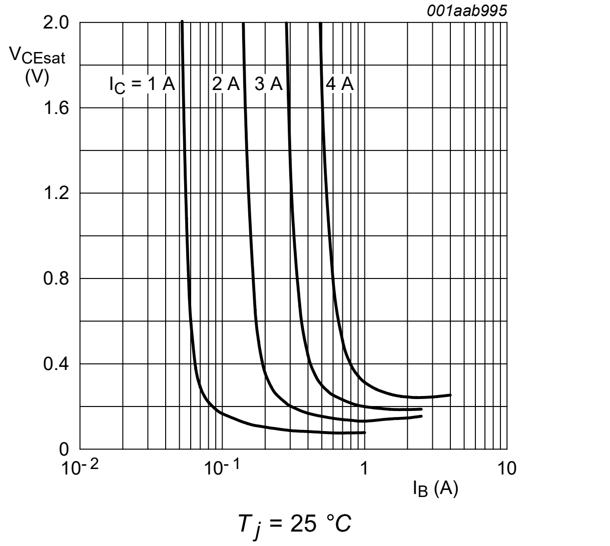


Fig. 6. Collector-emitter saturation voltage as a function of base current; typical values

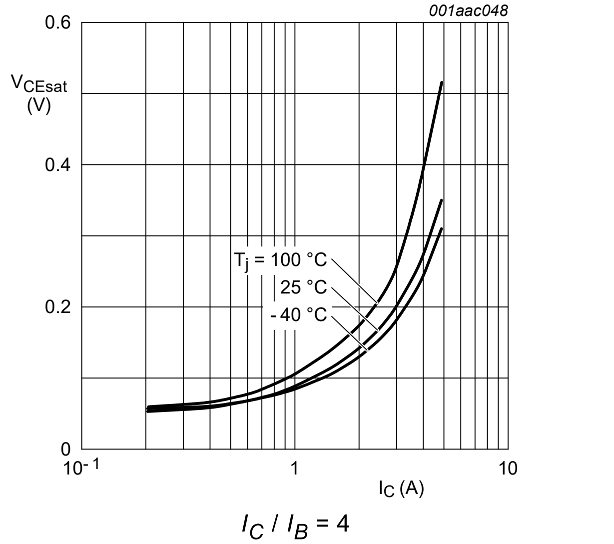


Fig. 7. Collector-emitter saturation voltage as a function of collector current; typical values

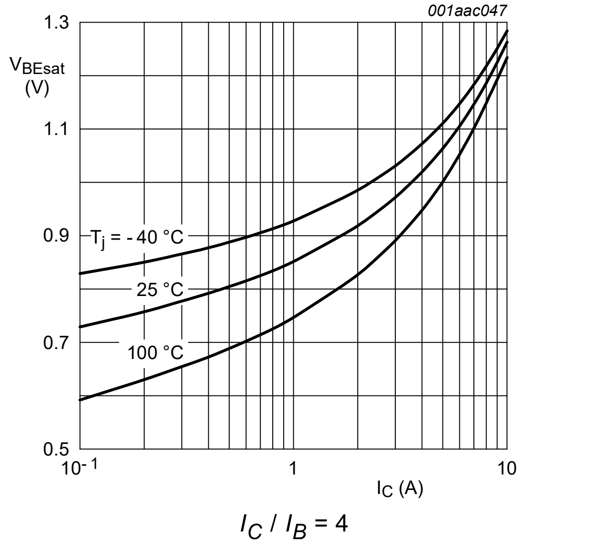


Fig. 8. Base-emitter saturation voltage as a function of collector current; typical values

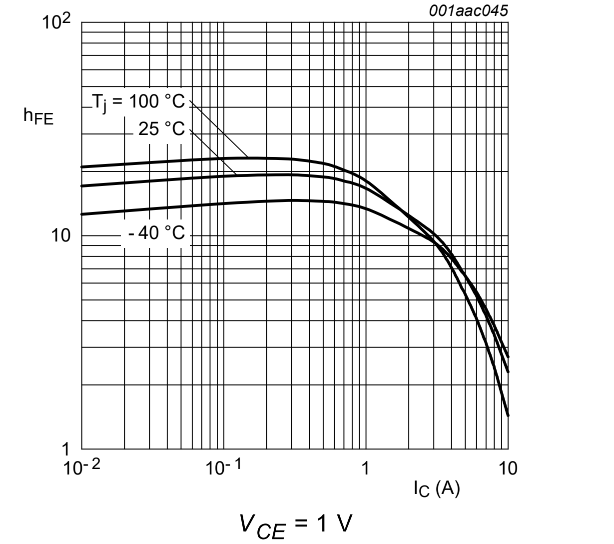
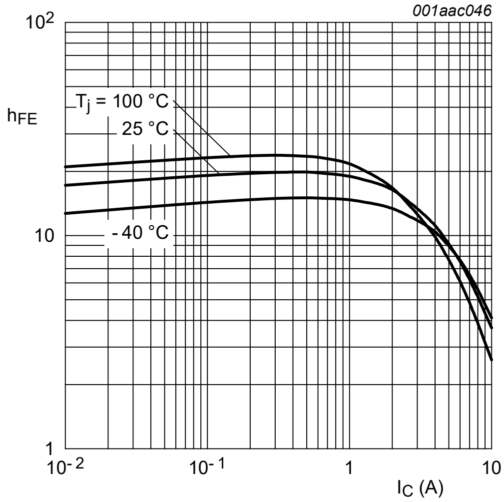
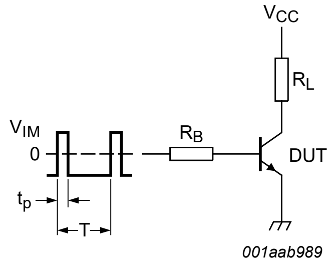


Fig. 9. DC current gain as a function of collector current; typical values



V_{CE} = 5 V

Fig. 10. DC current gain as a function of collector current; typical values



$V_{IM} = -6$ to $+8$ V; $V_{CC} = 250$ V; $t_p = 20$ μs; $\delta = \frac{t_p}{T} = 0.01$

R_B and R_L calculated from I_{Con} and I_{Bon} requirements.

Fig. 11. Test circuit for resistive load switching

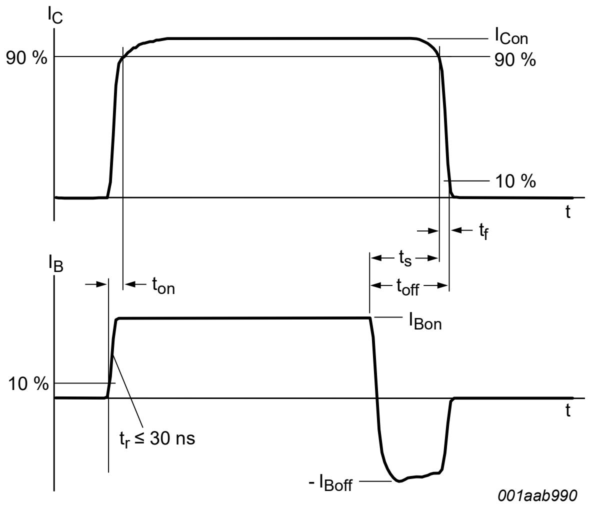
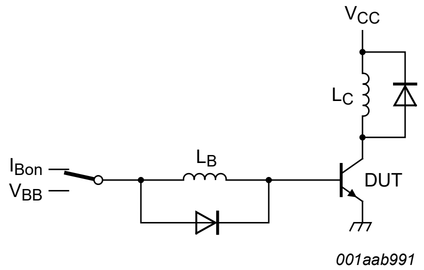


Fig. 12. Switching times waveforms for resistive load



$V_{CC} = 300$ V; $V_{BB} = -5$ V; $L_C = 200$ μH; $L_B = 1$ μH

Fig. 13. Test circuit for inductive load switching

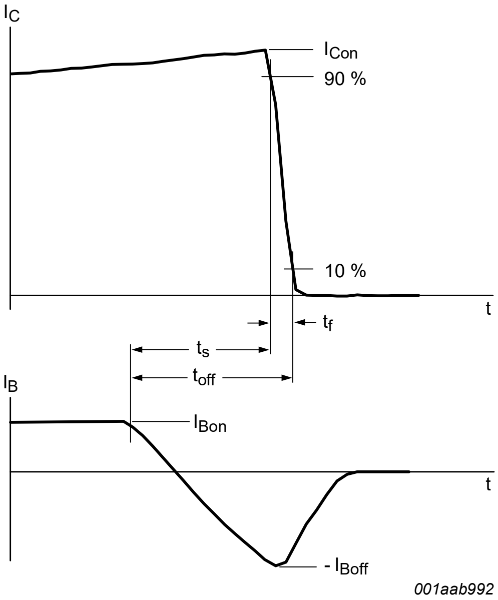
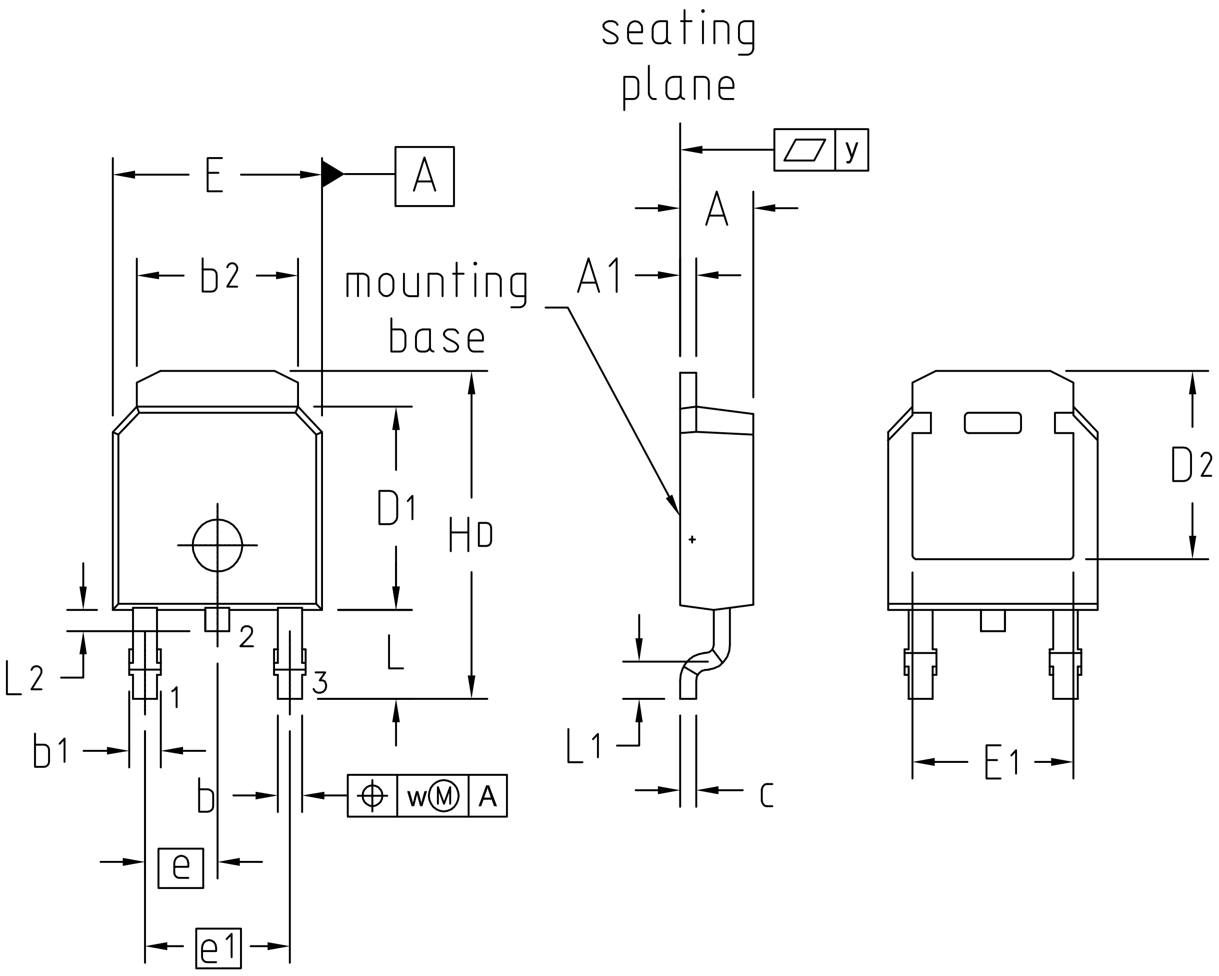


Fig. 14. Switching times waveforms for inductive load

9. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) SOT428



UNIT	A	A_1	b	b_1	b_2	c	D_1	D_2	E	E_1	e	e_1	H_D	L	L_1	L_2	w	y
mm	2.38	0.93	0.89	1.1	5.46	0.56	6.22	4.00	6.73	4.45	2.285	4.57	10.40	2.95	0.5	0.90	0.2	0.20
	2.22	0.46	0.71	0.9	5.00	0.20	5.98	min.	6.47	min.			9.60	2.55	min.	0.50		max.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT428		TO-252				

Fig. 15. Package outline DPAK (SOT428)

10. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".
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